

Silicon Switching Diode BAS16TT1G

3

CASE 463 SOT-416 STYLE 2

Features

 These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Continuous Reverse Voltage	V_R	100	V
Recurrent Peak Forward Current	I _F	200	mA
Peak Forward Surge Current Pulse Width = 10 μs	I _{FM(surge)}	500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, FR-4 Board (Note 1) T _A = 25°C	P _D	225	mW
Derated above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ heta JA}$	555	°C/W
Total Device Dissipation, FR-4 Board (Note 2) T _A = 25°C Derated above 25°C	P _D	360 2.9	mW mW/°C
			,
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	345	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	−55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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- 1. FR-4 @ Minimum Pad
- 2. FR-4 @ 1.0 × 1.0 Inch Pad



MARKING DIAGRAM



XX = Specific Device Code

M = Date Code

Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
BAS16TT1G	SOT-416 (Pb-Free)	3000 / Tape & Reel
NSVBAS16TT1G	SOT-416 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Forward Voltage $ \begin{aligned} &(I_F=1.0 \text{ mA})\\ &(I_F=10 \text{ mA})\\ &(I_F=50 \text{ mA})\\ &(I_F=150 \text{ mA}) \end{aligned} $	V _F	- - - -	715 866 1000 1250	mV
Reverse Current $(V_R = 100 \text{ V})$ $(V_R = 75 \text{ V}, T_J = 150^{\circ}\text{C})$ $(V_R = 25 \text{ V}, T_J = 150^{\circ}\text{C})$	I _R	- - -	1.0 50 30	μΑ
Capacitance (V _R = 0, f = 1.0 MHz)	C _D	-	2.0	pF
Reverse Recovery Time ($I_F = I_R = 10$ mA, $R_L = 50 \Omega$) (Figure 1)	t _{rr}	-	6.0	ns
Stored Charge (I _F = 10 mA to V _R = 6.0 V, R _L = 500 Ω) (Figure 2)	QS	-	45	PC
Forward Recovery Voltage ($I_F = 10 \text{ mA}, t_r = 20 \text{ ns}$) (Figure 3)	V _{FR}	-	1.75	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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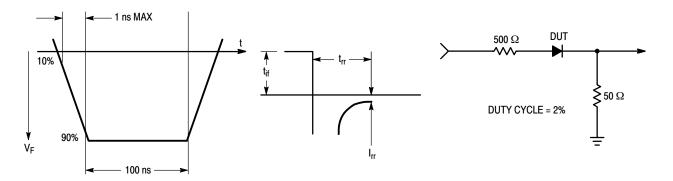


Figure 1. Reverse Recovery Time Equivalent Test Circuit

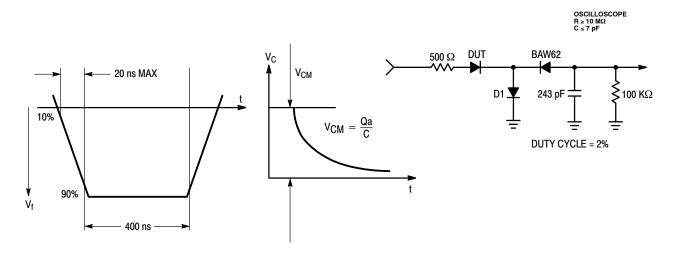


Figure 2. Stored Charge Equivalent Test Circuit

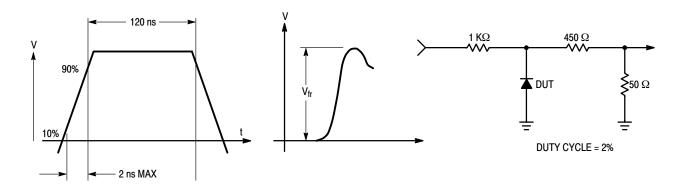
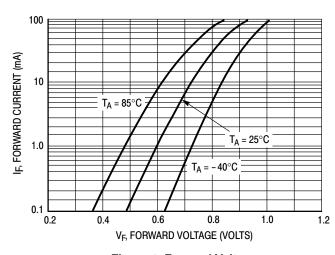


Figure 3. Forward Recovery Voltage Equivalent Test Circuit

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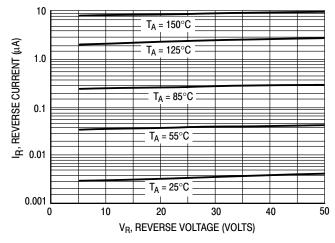


Figure 4. Forward Voltage

Figure 5. Leakage Current

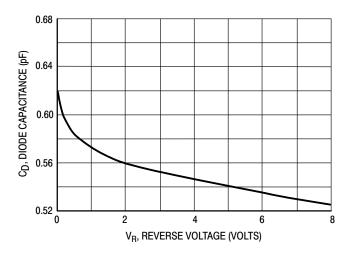


Figure 6. Capacitance

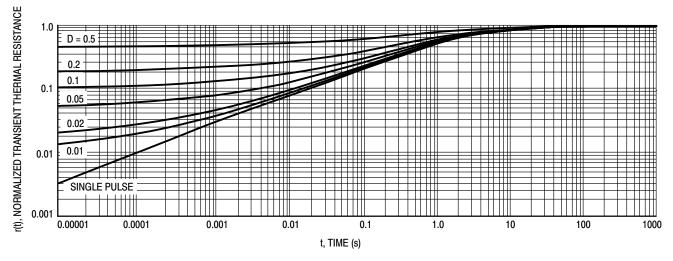


Figure 7. Normalized Thermal Response



SC75-3 1.60x0.80x0.80, 1.00P

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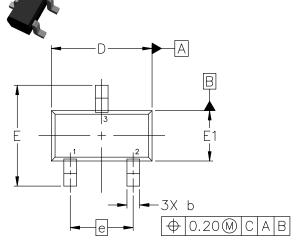
DATE 01 FEB 2024

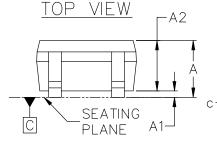
NOTES:

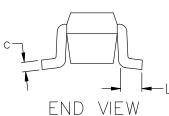
- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.

DIM	MILLIMETERS			
	MIN.	NOM.	MAX.	
А	0.70	0.80	0.90	
A1	0.00	0.05	0.10	
A2	0.80 REF.			
b	0.15	0.20	0.30	
С	0.10	0.15	0.25	
D	1.55	1.60	1.65	
Е	1.50	1.60	1.70	
E1	0.70	0.80	0.90	
е	1.00 BSC			
L	0.10	0.15	0.20	

-0.356







SIDE VIEW

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

Μ = Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:	
PIN 1. BASE	
O EMITTED	

STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE

3. COLLECTOR

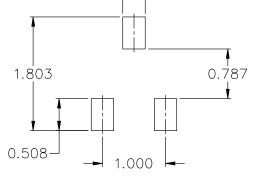
STYLE 2: PIN 1. ANODE 2. N/C 3. CATHODE

STYLE 5: PIN 1. GATE 2. SOURCE 3. DRAIN

STYLE 3: PIN 1. ANODE 2. ANODE 3 CATHODE

RECOMMENDED MOUNTING FOOTPRINT* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY

AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



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DESCRIPTION:

SC75-3 1.60x0.80x0.80, 1.00P

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